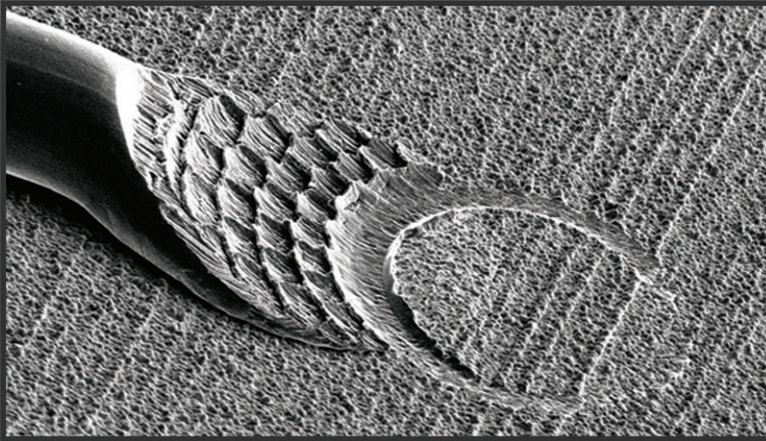
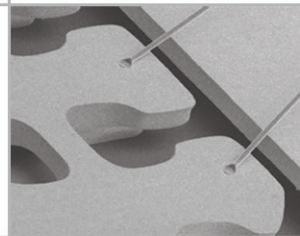


# SF

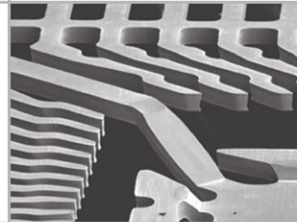
STITCH FUSION



STITCH BOND. REDEFINED.

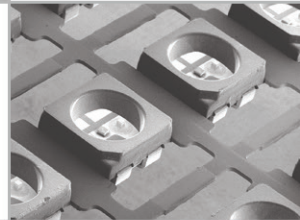


QFN



LED

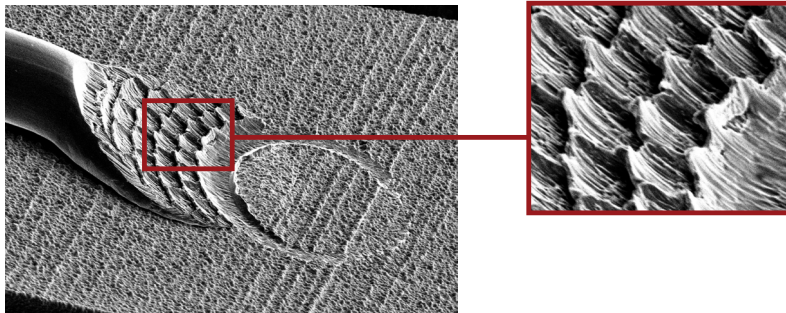
ROUGHENED L/F



Copper Wire bonding in advanced packaging, such as multiple stack dies with BSOB bonding, roughened leadframes poses challenges in meeting bond reliability and stringent requirements in bonding yields. SPT's SF capillary is developed with Swiss precision state-of-the-art surface finishing technology to achieve a new level of 2nd bond performance for challenging substrates or leadframes.

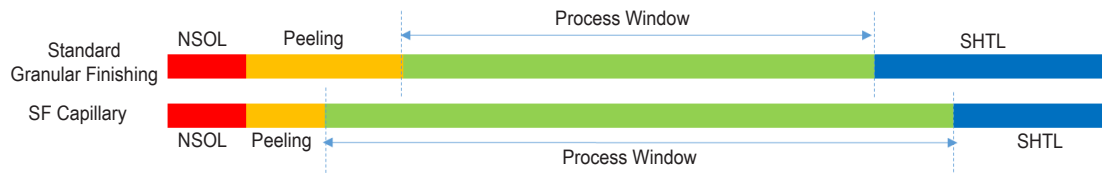
## Capability

Engineered surface morphology. Superior gripping for challenging packages.



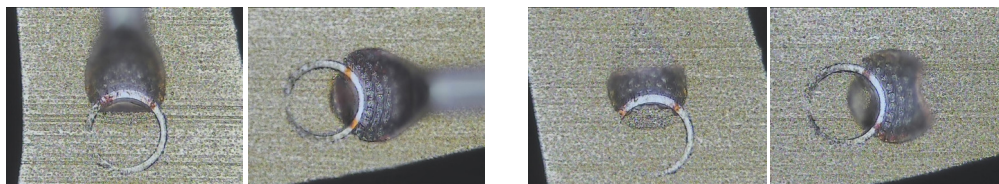
## Bondability

Robust process window.



## Reliability

Surpassed automotive requirements.



Stable tail termination and elimination stitch peeling

Consistent stitch pull failure mode

■ Please contact our SPT local sales representative for technical advice and recommendations.